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PATENT APPLICATION
Office of
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TECHNOLOGY CENTER 2800
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Satoshi TAKANO

Group Art Unit: 2825

Application No.: 09/819,690

Examiner: G. Lee

Filed: March 29, 2001

Docket No.: 109107

For: SEMICONDUCTOR MANUFACTURING METHOD, SUBSTRATE PROCESSING
METHOD, AND SEMICONDUCTOR MANUFACTURING APPARATUS

SUPPLEMENTAL AMENDMENT

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

Further to the Amendment filed April 7, 2003, please further amend the above-
identified application as follows:

IN THE CLAIMS:

Please cancel claims 7 and 8 without prejudice to or disclaimer of the subject matter
contained therein.

Please replace claims 1-3, 6 and 9-11 as follows:

1. (Twice Amended) A semiconductor manufacturing method, comprising the
steps of:

exchanging a substrate between a preliminary chamber and an external part;
subjecting the substrate to predetermined processing in a process chamber; and
transferring the substrate through a transfer chamber provided between said
preliminary chamber and said process chamber,

wherein said substrate transferring step comprises the following three steps: